ABSTRACT

An integrated circuit incorporates flip chip and wire bonding techniques to provide an improved integrated circuit device. The integrated circuit device includes a package having a first plurality of bonding pads and a semiconductor substrate within the integrated circuit package and including a second plurality of bonding pads. A semiconductor substrate has a surface area. A plurality of wire bonds connect the first plurality of bonding pads to the second plurality of bonding pads. The device further includes an interconnection substrate mounted on the semiconductor substrate. The interconnection substrate has a surface area smaller than the semiconductor substrate surface area.